8 3Y

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- EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Typical V<sub>OLP</sub> (Output Ground Bounce)
   < 0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)
   2 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Inputs Accept Voltages to 5.5 V
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages

#### D, DB, OR PW PACKAGE (TOP VIEW) 14 🛮 V<sub>CC</sub> 10E 1A [ 2 13 4OE 1Y **∏** 2<del>0Ε</del> Π 11 **∏** 4Y 2A [ 5 10 3 3 3 3 3 S E 2Y 🛮 9 3A

GND [

#### description

This quadruple bus buffer gate is designed for 1.65-V to 3.6-V V<sub>CC</sub> operation.

The SN74LVC125A features independent line drivers with 3-state outputs. Each output is disabled when the associated output-enable ( $\overline{OE}$ ) input is high.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

The SN74LVC125A is characterized for operation from -40°C to 85°C.

### FUNCTION TABLE (each buffer)

INPU	JTS	OUTPUT
OE	Α	Υ
L	Н	Н
L	L	L
Н	Χ	Z



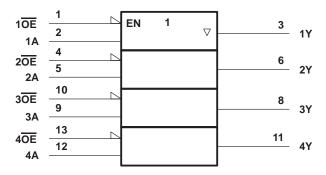
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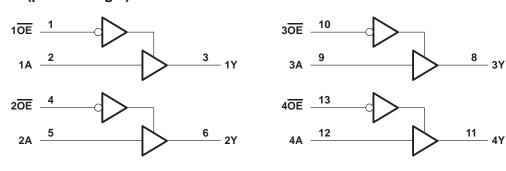
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#### logic symbol<sup>†</sup>



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

#### logic diagram (positive logic)



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V <sub>CC</sub>		–0.5 V to 6.5 V
Input voltage range, V <sub>I</sub> (see Note 1)		–0.5 V to 6.5 V
Output voltage range, VO (see Notes 1 and 2)		$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{IK}$ ( $V_I < 0$ )		
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)		
Continuous output current, IO		±50 mA
Continuous current through V <sub>CC</sub> or GND		±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3):	D package	127°C/W
-	DB package	158°C/W
	PW package	170°C/W
Storage temperature range, T <sub>stg</sub>		–65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stressratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. The value of V<sub>CC</sub> is provided in the recommended operating conditions table.
- 3. The package thermal impedance is calculated in accordance with JESD 51.



#### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
Voc	Supply voltage	Operating  Data retention only		3.6	V	
Vcc	Supply voltage				V	
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	$0.65 \times V_{CC}$			
٧ıH	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		0.35 × V <sub>CC</sub>		
VIL	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		
٧ <sub>I</sub>	Input voltage		0	5.5	V	
Vo	Output voltage		0	Vcc	V	
		V <sub>CC</sub> = 1.65 V		-4		
la	High level output ourrent	V <sub>CC</sub> = 2.3 V		-8	mA	
ІОН	High-level output current	$V_{CC} = 2.7 \text{ V}$		-12	ma	
		V <sub>CC</sub> = 3 V		-24		
		V <sub>CC</sub> = 1.65 V		4		
IOL Low-level or	Laurianal autorit aumant	V <sub>CC</sub> = 2.3 V		8	mA	
	Low-level output current	$V_{CC} = 2.7 \text{ V}$		12		
		V <sub>CC</sub> = 3 V		24		
Δt/Δν	Input transition rise or fall rate		0	8	ns/V	
TA	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP <sup>†</sup>	MAX	UNIT
	I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> -0.2			
	I <sub>OH</sub> = -4 mA	1.65 V	1.2			
V	I <sub>OH</sub> = -8 mA	2.3 V	1.7			٧
VOH	1 10 1	2.7 V	2.2			
	IOH = -12  mA	3 V	2.4			
	I <sub>OH</sub> = -24 mA	3 V	2.2			
	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V			0.2	
	I <sub>OL</sub> = 4 mA	1.65 V			0.45	
$V_{OL}$	I <sub>OL</sub> = 8 mA	2.3 V			0.7	V
	I <sub>OL</sub> = 12 mA	2.7 V			0.4	
	I <sub>OL</sub> = 24 mA	3 V			0.55	
Ι <sub>Ι</sub>	V <sub>I</sub> = 5.5 V or GND	3.6 V			±5	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V			10	μΑ
∆ICC	One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V			500	μΑ
C <sub>i</sub>	$V_I = V_{CC}$ or GND	3.3 V		5		pF

<sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



### SN74LVC125A QUADRUPLE BUS BUFFER GATE WITH 3-STATE OUTPUTS

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# switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER FROM TO (OUTPUT)		V <sub>CC</sub> = ± 0.1				V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT	
	(1141 01)	(0011 01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
<sup>t</sup> pd	А	Y	1	12.3	1	6.3		5.5	1	4.8	ns
t <sub>en</sub>	ŌĒ	Y	1	14.3	1	7.4		6.6	1	5.4	ns
<sup>t</sup> dis	ŌĒ	Y	1	11.1	1	5.6		5	1	4.6	ns
t <sub>sk(o)</sub> †										1	ns

<sup>†</sup> Skew between any two outputs of the same package switching in the same direction

### operating characteristics, T<sub>A</sub> = 25°C

PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V ± 0.15 V	V <sub>CC</sub> = 2.5 V ± 0.2 V	V <sub>CC</sub> = 3.3 V ± 0.3 V	UNIT
			TYP	TYP	TYP	
C <sub>pd</sub>	Power dissipation capacitance per gate	f = 10 MHz	7.4	11.3	15	pF



**VCC** 

0 V

**VCC** 

0 V

VCC

- Vol

VOH

- 0 V

V<sub>CC</sub>/2

V<sub>CC</sub>/2

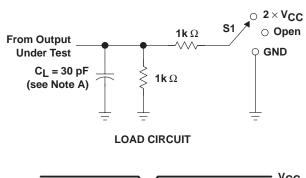
- tpLZ

V<sub>OL</sub> + 0.15 V

V<sub>OH</sub> - 0.15 V

- tPHZ

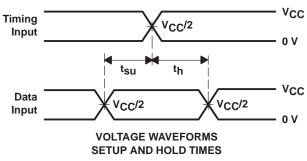
#### PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 V \pm 0.15 V$

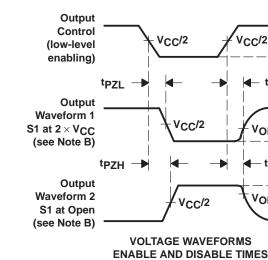


TEST	<b>S1</b>
t <sub>pd</sub>	Open
tPLZ/tPZL	2×V <sub>CC</sub>
tPHZ/tPZH	Open

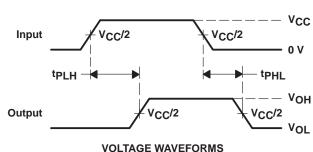
V<sub>CC</sub>/2

**VOLTAGE WAVEFORMS PULSE DURATION** 





Input



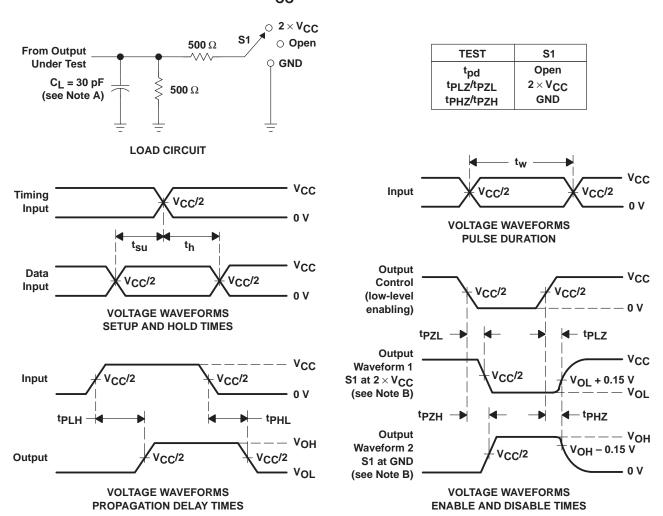
**PROPAGATION DELAY TIMES** NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_0 = 50 \Omega$ ,  $t_f \leq$  2 ns,  $t_f \leq$  2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



## PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



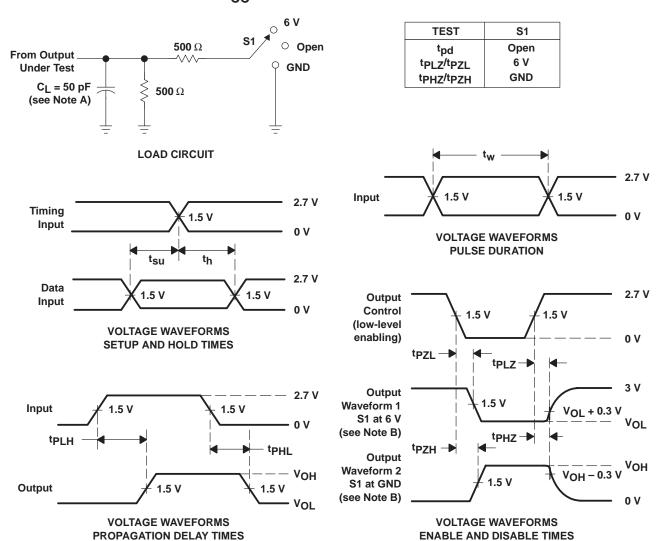
NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq$  2 ns.  $t_f \leq$  2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzl and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



### PARAMETER MEASUREMENT INFORMATION $V_{CC}$ = 2.7 V AND 3.3 V $\pm$ 0.3 V



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \,\Omega$ ,  $t_f \leq$  2.5 ns.  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms

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